soitec

INVESTOR CONFERENCE

AI x CONNECTIVITY POWERED BY ENGINEERED SUBSTRATES

Barcelona | March 2025

DISCLAIMER

This document is provided by Soitec (the "Company") for information purposes only.

The Company's business operations and financial position are described in the Company's 2023-2024 Universal Registration Document (which notably includes the 2023-2024 Annual Financial Report) which was filed on June 5, 2024 with the French stock market authority (Autorité des Marchés Financiers, or AMF) under number D.23-0482, as well as in the 2024-2025 half-year financial report released on November 20, 2024. The French version of the 2023-2024 Universal Registration Document and the 2024-2025 half-year financial report, together with English courtesy translation for information purposes, are available for consultation on the Company's website (www.soitec.com), in the section Company - Investors - Financial Reports.

Your attention is drawn to the risk factors described in Chapter 2.1 (Risk factors and controls mechanism) of the Company's 2023-2024 Universal Registration Document.

This document contains summary information and should be read in conjunction with the 2023-2024 Universal Registration Document and the 2024-2025 half-year financial report.

This document contains certain forward-looking statements. These forward-looking statements relate to the Company's future prospects, developments and strategy and are based on analyses of earnings forecasts and estimates of amounts not yet determinable. By their nature, forward-looking statements are subject to a variety of risks and uncertainties as they relate to future events and are dependent on circumstances that may or may not materialize in the future. Forward-looking statements are not a guarantee of the Company's future performance. The occurrence of any of the risks described in Chapter 2.1 (Risk factors and controls mechanism) of the 2023-2024 Universal Registration Document may have an impact on these forward-looking statements. In particular, the future consequences of geopolitical conflicts, notably the Ukraine / Russia situation, as well as rising inflation, may result in greater impacts than currently anticipated in these forward-looking statements.

The Company's actual financial position, results and cash flows, as well as the trends in the sector in which the Company operates may differ materially from those contained in this document. Furthermore, even if the Company's financial position, results, cash-flows and the developments in the sector in which the Company operates were to conform to the forward-looking statements contained in this document, such elements cannot be construed as a reliable indication of the Company's future results or developments.

The Company does not undertake any obligation to update or make any correction to any forward-looking statement in order to reflect an event or circumstance that may occur after the date of this document. In addition, the occurrence of any of the risks described in Chapter 2.1 (Risk factors and controls mechanism) of the 2023-2024 Universal Registration Document may have an impact on these forward-looking statements.

This document does not constitute or form part of an offer or a solicitation to purchase, subscribe for, or sell the Company's securities in any country whatsoever. This document, or any part thereof, shall not form the basis of, or be relied upon in connection with, any contract, commitment or investment decision.

Notably, this document does not constitute an offer or solicitation to purchase, subscribe for or to sell securities in the United States. Securities may not be offered or sold in the United States absent registration or an exemption from the registration under the U.S. Securities Act of 1933, as amended (the "Securities Act"). The Company's shares have not been and will not be registered under the Securities Act. Neither the Company nor any other person intends to conduct a public offering of the Company's securities in the United States.

#01

AI x CONNECTIVITY UPGRADING NETWORKS AND DEVICES

#02

AI x CONNECTIVITY SUPPORTING SOITEC EXPANSION

#03

AI x CONNECTIVITY ENHANCED BY ENGINEERED SUBSTRATES

01 AI x CONNECTIVITY UPGRADING NETWORKS & DEVICES

CONVERGING THE CONNECTIVITY AND AI REVOLUTIONS

Mobile x Infrastructure x NTN
5G Advanced, Wi-Fi 6/6E/7/8, FWA, NTN for enhanced mobile broadband experience

Next-Gen User Devices
On-the-go augmented & virtual reality, wearables / hearables and connected home

Advanced Virtual Assistants
Fast, adaptive & simplified complex tasks for greater efficiency

Real-Time processing
Capture studio-quality image & break language barriers, even without network

Industry 4.0
Intelligent factories, warehouses, predictive maintenance

Smart City x Transportation
Connected, safer, autonomous vehicles paving the way for a sustainable wireless world

Enhanced Security
AI at the edge for greater privacy & enhanced data protection

AI-Generated Content
Speed up creation, enhance quality, personalize content, and boost productivity

AI x CONNECTIVITY
5G: SUSTAINED GROWTH IN GLOBAL MOBILE DATA TRAFFIC

5G DATA TRAFFIC ACCELERATION BEYOND 2024

x2.7
5G MOBILE SUBSCRIPTIONS
6.3B IN 2030

x2.2
FIXED WIRELESS ACCESS CONNECTIONS
350M IN 2030

x2.0
AVERAGE DATA CONSUMPTION PER SMARTPHONE
40GB / MONTH IN 2030

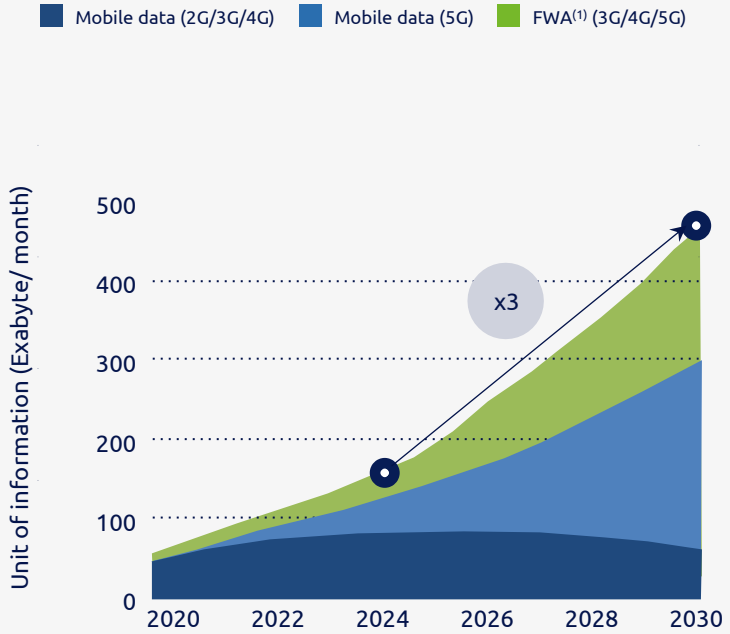
Public & private networks

Smart transportation

Massive IoT

Industry 4.0

5G enabling significant data traffic growth



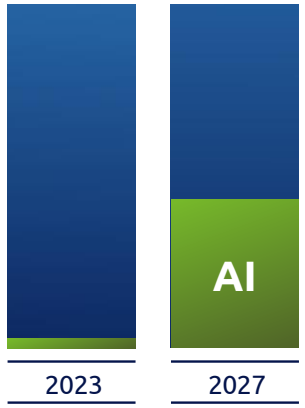
Source: Ericsson Mobility report November 2024

(1) Fixed Wireless Access

AI x CONNECTIVITY
FURTHER BOOSTING MOBILE DATA DEMAND

On-device AI: the new personal assistant

AI smartphones to reach more than 40% of total volumes

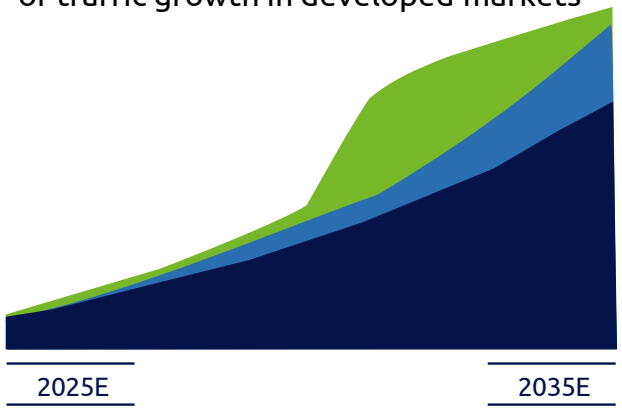


Boosting mobile network traffic

Bull case: AI booming coupled with AR glasses adoption

Base case: increased penetration of Edge AI driving steady demand in data

Bear case: AI to offset slight slow-down of traffic growth in developed markets



Driving demand in high-performance RF

To enable greater data processing, lower latency, lower energy consumption, better thermal management and reduced footprint

Source: Qorvo, Ericsson Mobility report November 2024

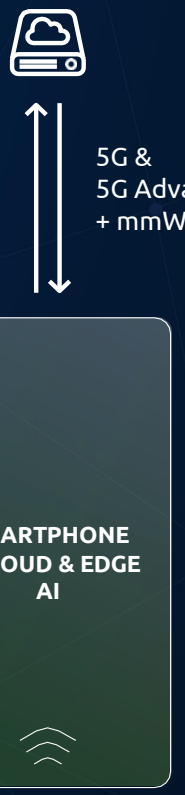
THE INTELLIGENCE REVOLUTION
MOVING BEYOND THE CONNECTIVITY REVOLUTION

CURRENT APPLICATIONS
- Computational photography
- Mobile gaming
- Voice assistant

CLOUD AI LIMITATIONS
- Latency
- Need for a reliable connection
- Privacy risk
- High power consumption in datacenters

SMARTPHONE + CLOUD AI

TODAY



FUTURE APPLICATIONS

- Advanced computational photography
- Desktop-level gaming on smartphone
- Augmented virtual companion
- Real-time language translation
- On-device text and image generation

BENEFITS OF EDGE AI

- Zero latency
- No connection required
- Privacy secured
- Low power consumption

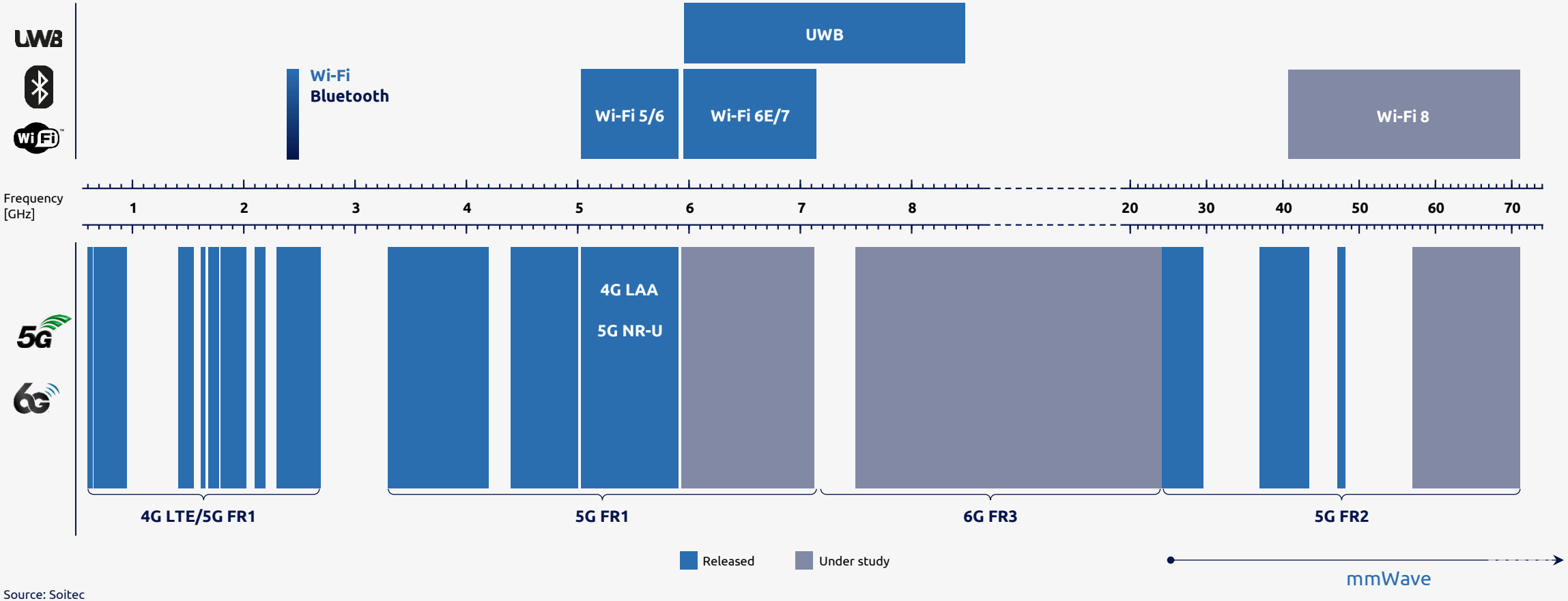
TOMORROW

Source: Qualcomm

AI x CONNECTIVITY

MORE FREQUENCY SPECTRA TO ACCOMMODATE AN INCREASING DATA TRAFFIC

Over the last 10 years, mobile data traffic has more than doubled on average every second year



Source: Soitec

AI x CONNECTIVITY – MOVING TO AN ALL-CONNECTED WORLD

5G PERFORMANCE vs 4G

x100 NETWORK CAPACITY

x10 SPEED

x10 FASTER RESPONSE TIME

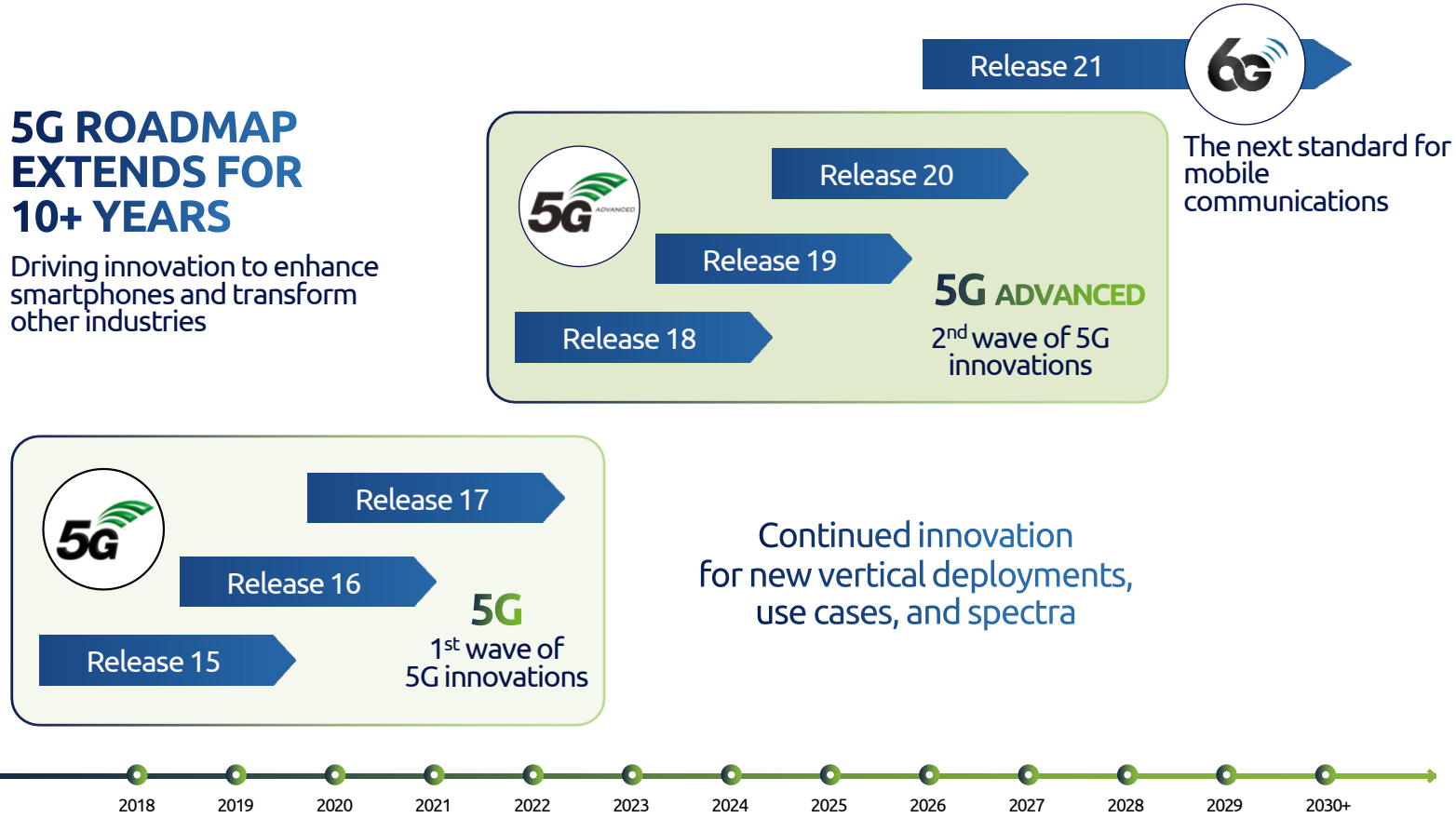
x10 CONNECTED DEVICES

x10 LESS ENERGY PER DATA

5G to 6G – PREPARING FOR A NEW ERA

5G ROADMAP EXTENDS FOR 10+ YEARS

Driving innovation to enhance smartphones and transform other industries



Source: Qualcomm, Ericsson

AI x CONNECTIVITY – ENHANCING Wi-Fi PERFORMANCE
ENABLING GREATER USER EXPERIENCES

Wi-Fi 6 / 6E / 7 pave the way for new wireless connectivity
Wi-Fi 8 is on the way

Driving innovation to enhance wireless connectivity for new experiences and extended range

Wi-Fi 8 — Immersive communication mmWave frequencies Ultra-low latency

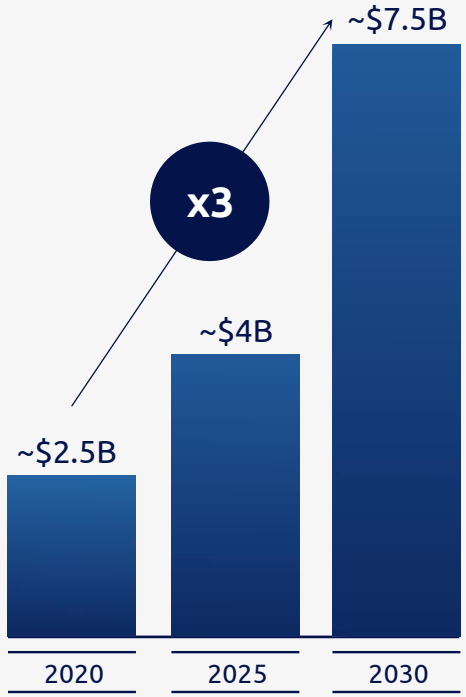
Wi-Fi 7 — Extremely High Throughput, low latency and/or high reliability for demanding applications from VR/AR to industrial IoT

Wi-Fi 6E — Adding 1GHz spectrum in the 6GHz band for higher quality of service (QoS) and secured connectivity

Wi-Fi 6 — High-speed connectivity technology in 2.4GHz and 5GHz bands for **smartphone, laptop, home, consolidating its place in smart home, wearables and automotive**

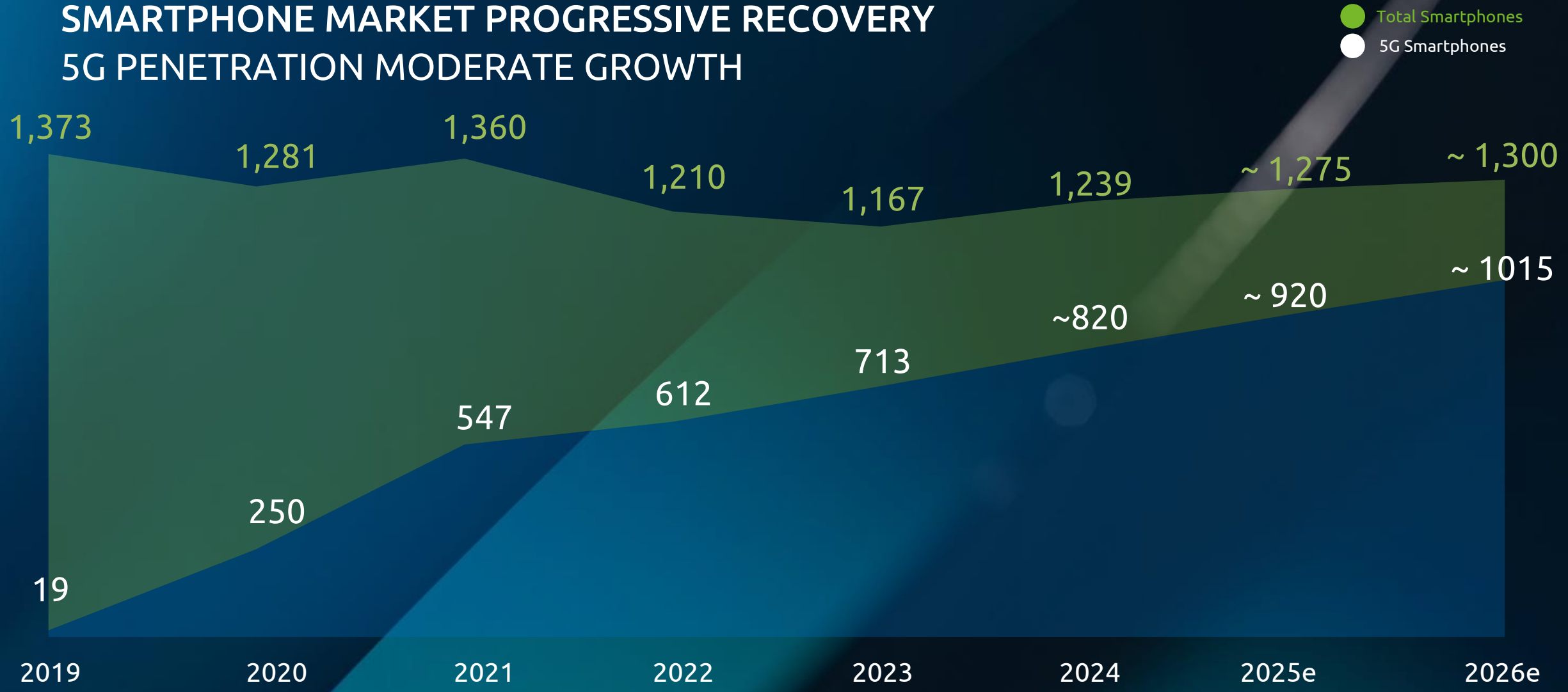
2019 2020 2021 2022 2023 2024 2025 2026 2027 2028 2029 2030+

Wi-Fi FRONT-END-MODULE SEMICONDUCTOR MARKET



Source: Soitec estimates

SMARTPHONE MARKET PROGRESSIVE RECOVERY
5G PENETRATION MODERATE GROWTH



Sources: IDC, Soitec estimates

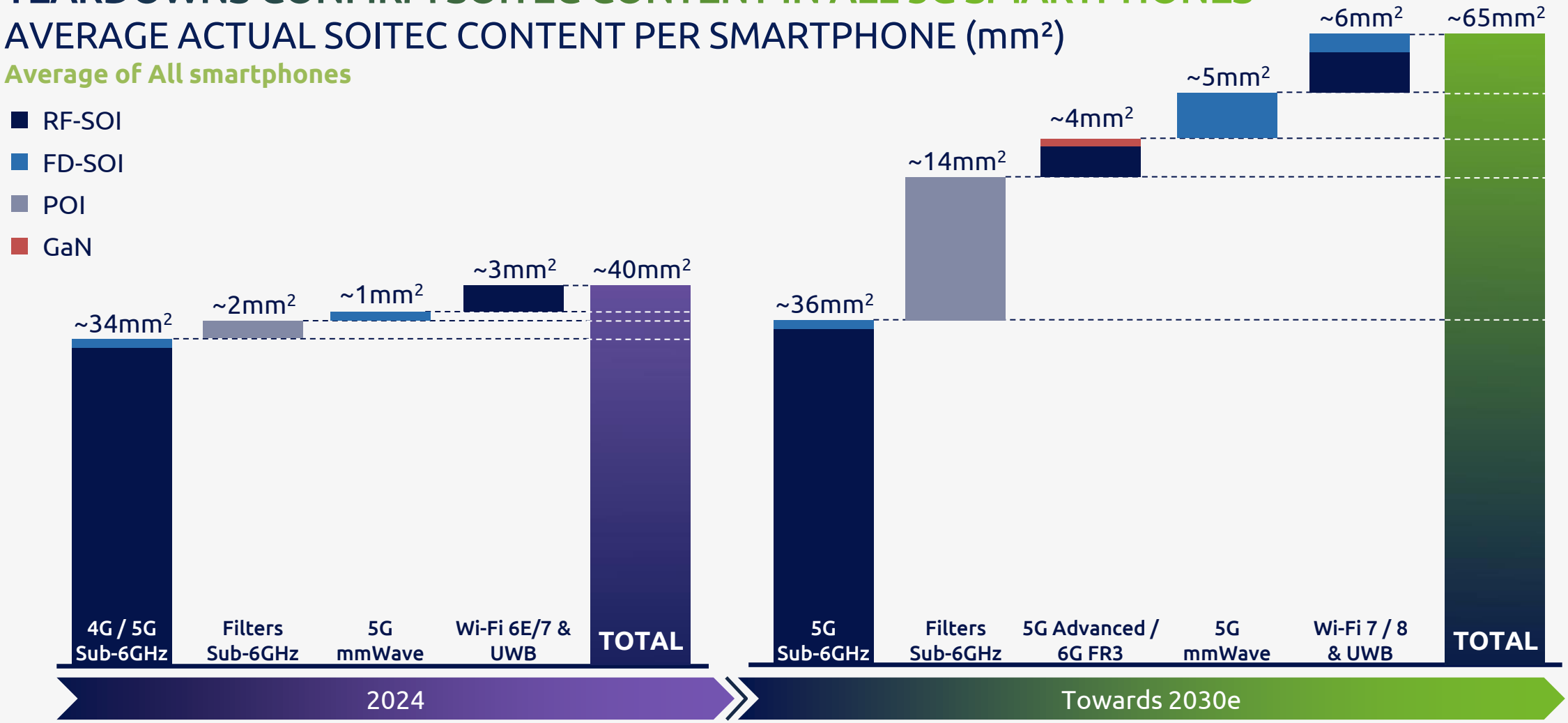
02

AI x CONNECTIVITY SUPPORTING SOITEC EXPANSION

TEARDOWNS CONFIRM SOITEC CONTENT IN ALL 5G SMARTPHONES

AVERAGE ACTUAL SOITEC CONTENT PER SMARTPHONE (mm²)

Average of All smartphones

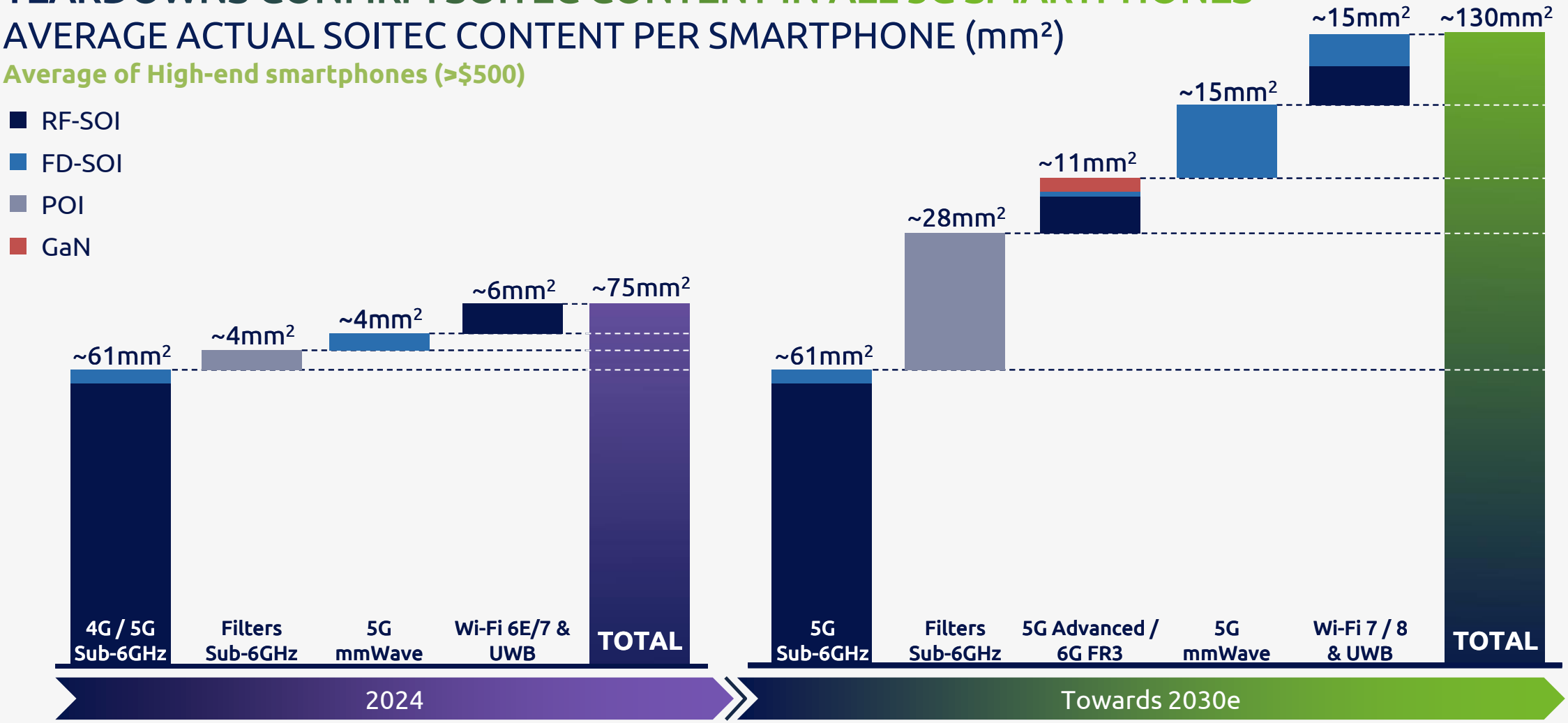


Source: Soitec

TEARDOWNS CONFIRM SOITEC CONTENT IN ALL 5G SMARTPHONES

AVERAGE ACTUAL SOITEC CONTENT PER SMARTPHONE (mm²)

Average of High-end smartphones (>$500)

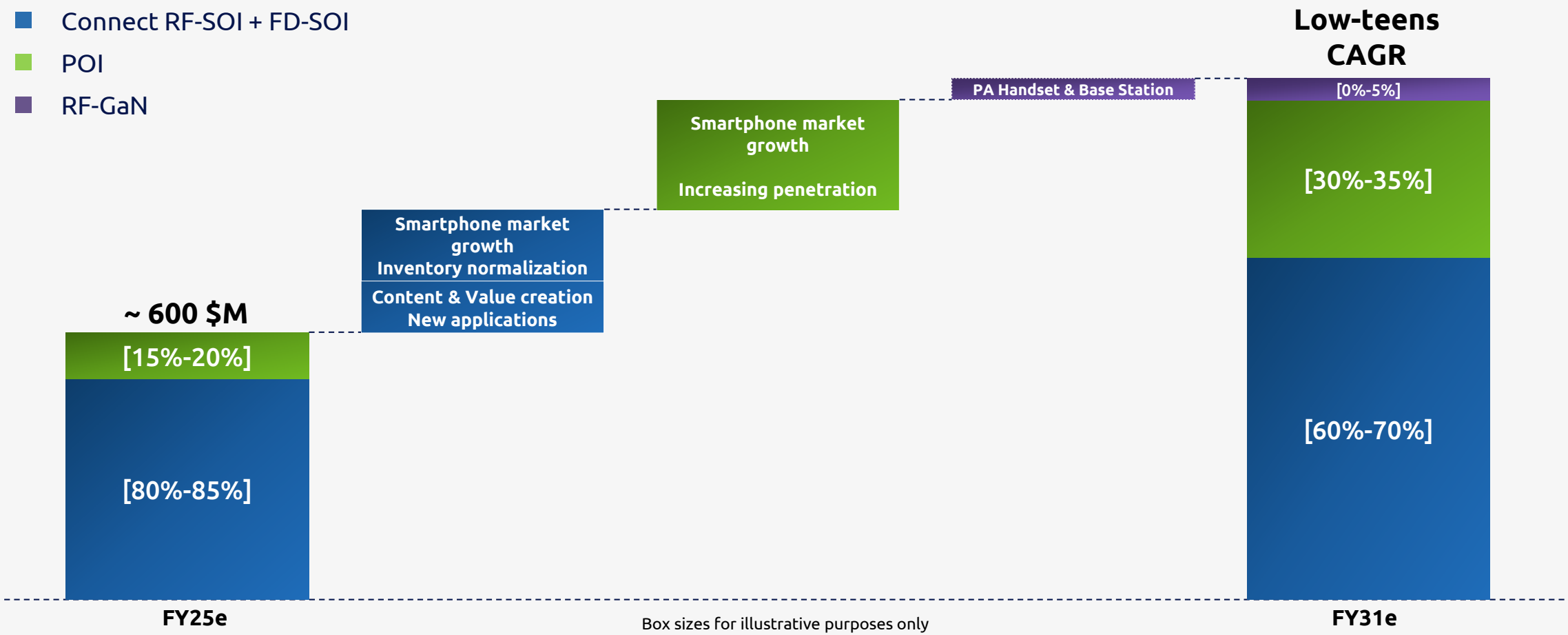


Source: Soitec

RF-SOI VALUE CHAIN INVENTORIES COMING DOWN

MOBILE COMMUNICATIONS DIVISION GROWTH DRIVERS

EXPANDING PRODUCT PORTFOLIO AND APPLICATIONS TO DELIVER LOW TEENS CAGR



INNOVATION TO SUPPORT CONTENT GROWTH AND VALUE CREATION

Enhanced connectivity & user experience

AI & ML
5G NR-U (6GHz)
5G FR3 (10-20GHz)
Wi-Fi 7

UWB
NTN 3GPP & proprietary sub-6GHz & mmWave

Enabling new technology differentiation for our customers

3D-stacking
Footprint optimization (die shrink)
Technology scaling (higher frequencies)

Foundry yield improvement

Advanced RF Performances

Enabling new devices

Form factor: increasing foldable phone market share leads to increasing antenna integration challenges

New devices (smart glasses, wearables) requiring optimized footprint

NEW PRODUCT INTRODUCTION TO STRENGTHEN LEADERSHIP
SUPPORTING RF-SOI SEGMENT SHARE IMPROVEMENT

GlobalFoundries' advanced 9SW platform to use Soitec's latest generation of 300mm RF-SOI wafers

"This collaboration with Soitec shows our commitment to ensure a continuous supply of high-performance RF-SOI solutions that meet our customers' fast evolving needs"

Soitec extends partnership with UMC to provide leading engineered substrates for industry's first 3D IC solution for RF-SOI

"Leveraging our strong partnership with Soitec, UMC's innovative 3D IC solution for RF-SOI has generated significant interest from customers as they seek to integrate more RF components in 5G-enabled wireless devices"

Tower Semiconductor sets a new RF-SOI standard with Broadcom's Wi-Fi RFFE modules for next-gen mobile applications

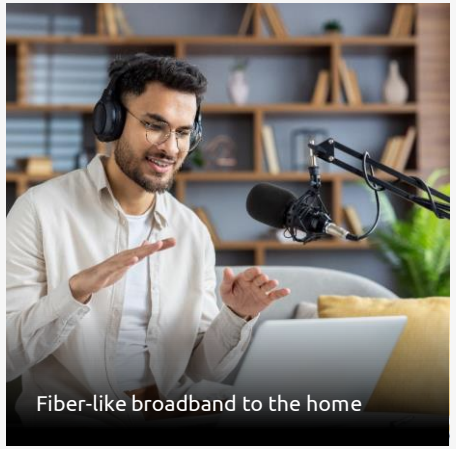
"The unique advantages of Tower's RF-SOI technology have enabled Broadcom to design and bring to market a set of compact, high-performance FEMs for Wi-Fi 7 mobile applications"

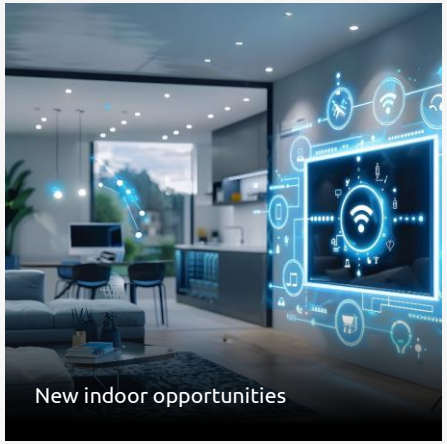
FIXED WIRELESS ACCESS – ENABLING FIBER TO THE HOME

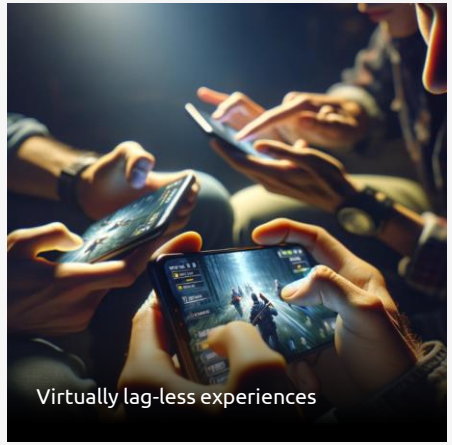
Last-mile technology with fiber-like data speeds

FWA networks could eliminate the need for “last-mile” fiber

5G mmWave further improves user experience through gigabit wireless and low latency services

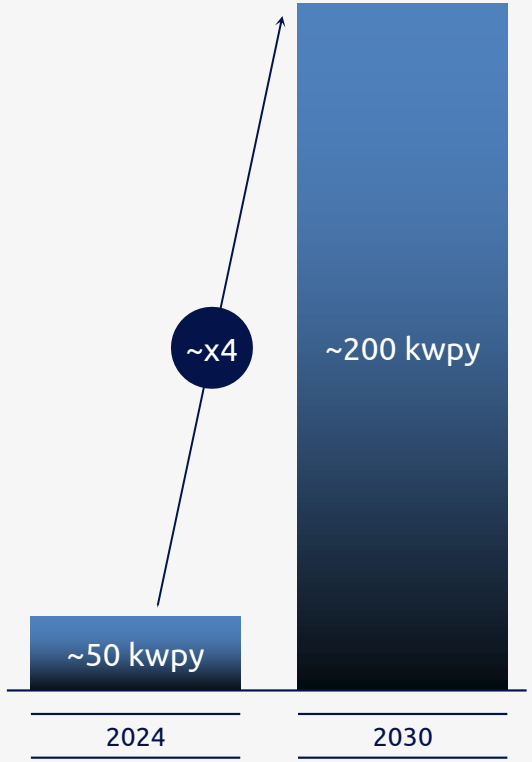






Sources: Soitec Estimates, Yole 2024

FIXED WIRELESS ACCESS CPE
FRONT-END-MODULE WAFER MARKET



Note: 8” equivalent
CPE: Customer Premises Equipment

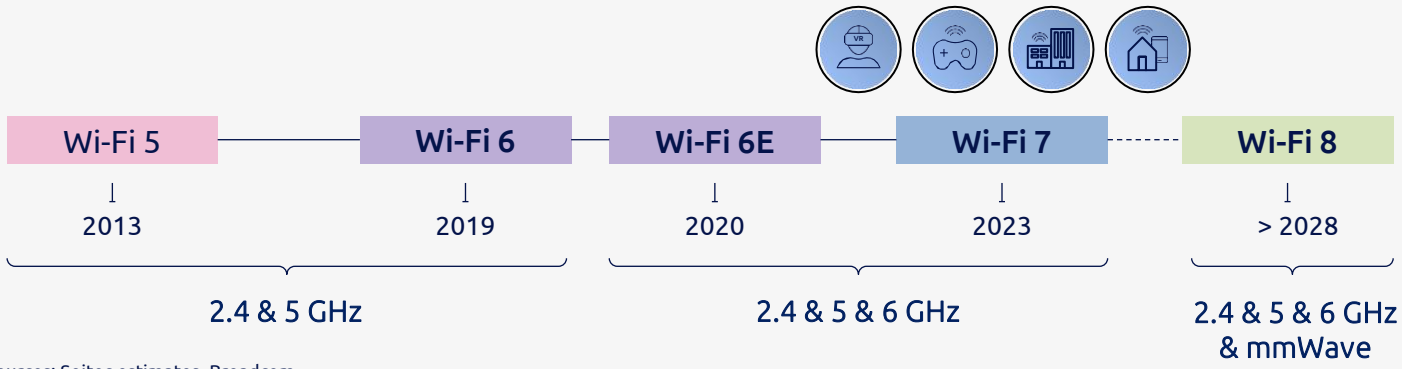
Wi-Fi 7/8 – TRANSITION TO FASTER CONNECTIVITY

x4
Performance per watt

x6
Faster response time

x60
Longer range

IMPROVED PERFORMANCE FOR Wi-Fi CONNECTIVITY ADDRESSES NEW USES CASES

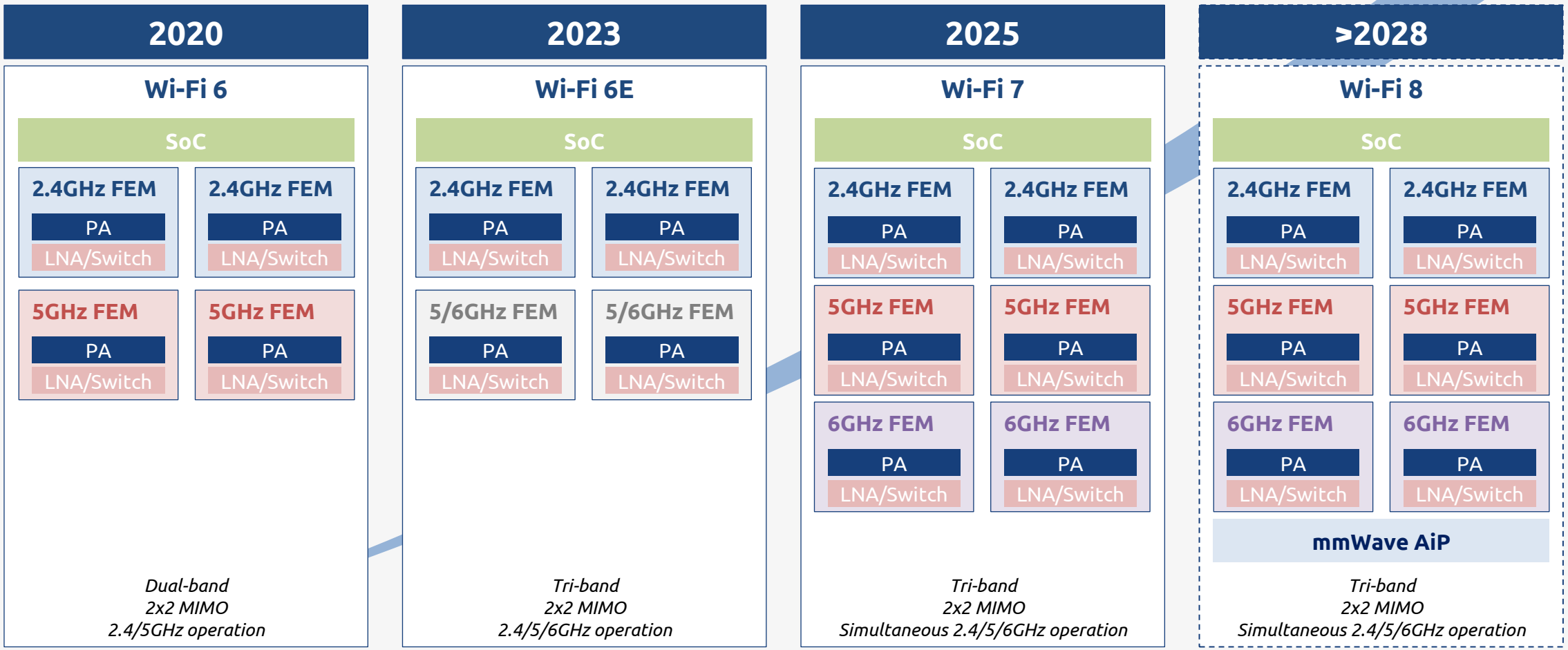


Wi-Fi CONNECTIVITY STANDARD SPLIT AMONG SMARTPHONE MARKET

Sources: Soitec estimates, Broadcom
x factors are on average, Wi-Fi 7 vs Wi-Fi 6

Wi-Fi 7/8 – FRONT END MODULE TRANSITION

UNLEASHING Wi-Fi FULL POTENTIAL WITH HIGHER CONTENT



Source: Yole 2024, Soitec consolidation

WIRELESS CONNECTIVITY IN AUTOMOTIVE

Source: Soitec

INFOTAINMENT
in-vehicle

Internet services
Navigation system
Screen mirroring

Hands free voice
Multimedia streaming

TELEMATICS
cloud ↔ vehicle
satellite ↔ vehicle

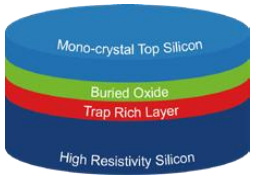
OTA Update
Vehicle location
Optimum routing

Internet access
Fleet utilization
Media services

ENVIRONMENT
V2x

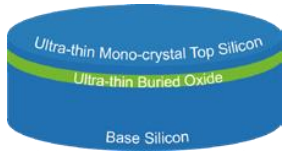
Dynamic traffic signage
Connection to home
Pedestrian warning

Driver assistance
Remote control
Keyless access



RF-SOI
Extended High performance RFFE for connectivity, C-V2X & 5G in automotive

FD-SOI
Extensive SoC solution from connectivity to MCU/PMU edge computing

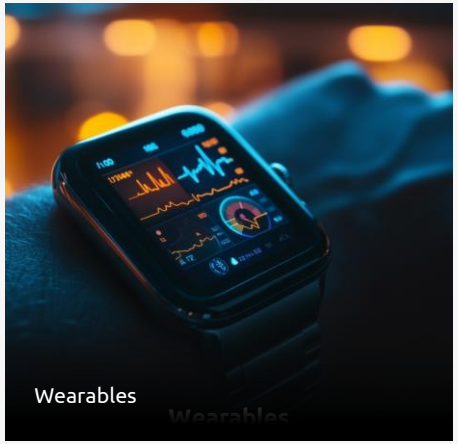


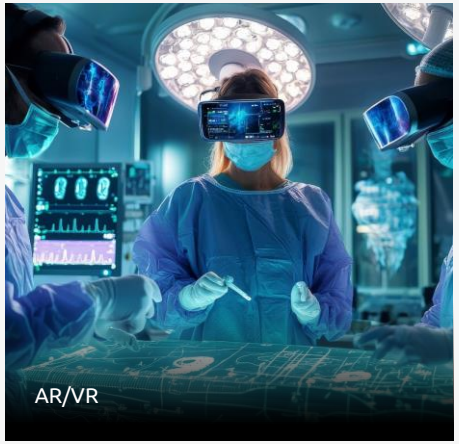
NEXT GENERATION OF CONNECTED DEVICES
RELIABLE, HIGH-BANDWIDTH & LOW-LATENCY CONNECTIVITY

5G Advanced and Wi-Fi 7 / 8 to support next-gen user devices challenges

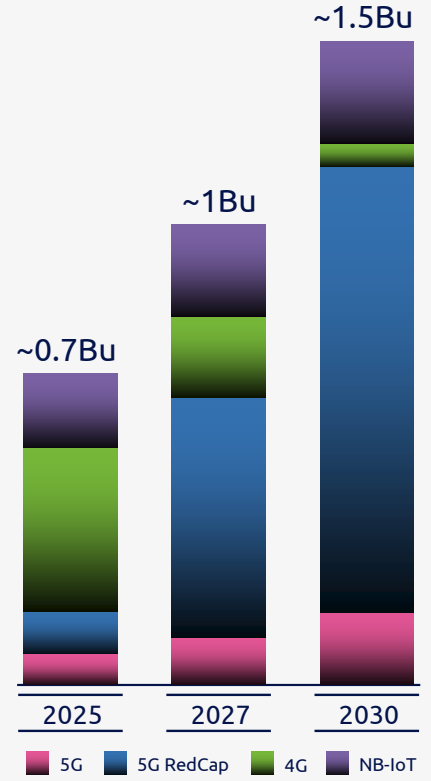
- Low power consumption devices for wearables
- Low latency and extended throughput for next gen AR / VR
- Higher location accuracy for personal trackers

APPLICATIONS EVOLVE TO BENEFIT FROM IMPROVED 5G ADVANCED TECHNOLOGY





NEXT-GEN USER DEVICES PER CELLULAR STANDARD



Source: Navian, 2024 (up to 2027) and Soitec consolidation >2027

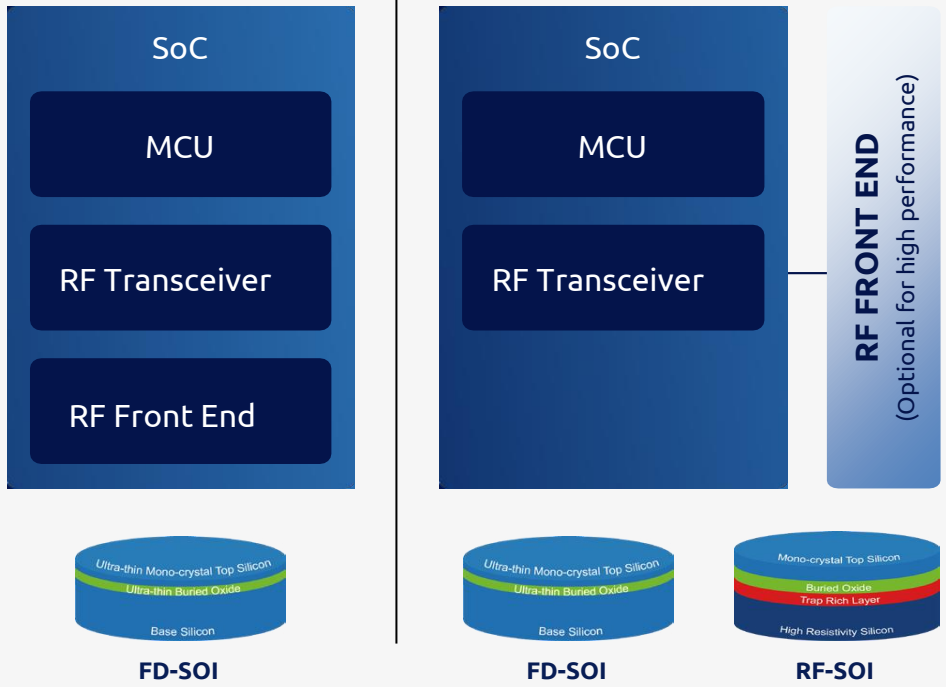
WIRELESS CONNECTIVITY IN SMART DEVICES

ENABLING WIRELESS FUNCTIONALITIES AT LOW POWER CONSUMPTION

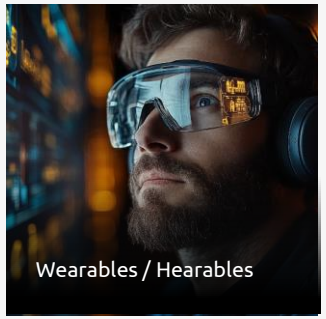
WIRELESS MODULES

MAINSTREAM
with integrated RFFE and low power consumption

HIGH END
with externalized RFFE and extended RF performances



POWER EFFICIENT WIRELESS SOLUTIONS SUPPORTING A WIDE RANGE OF APPLICATIONS



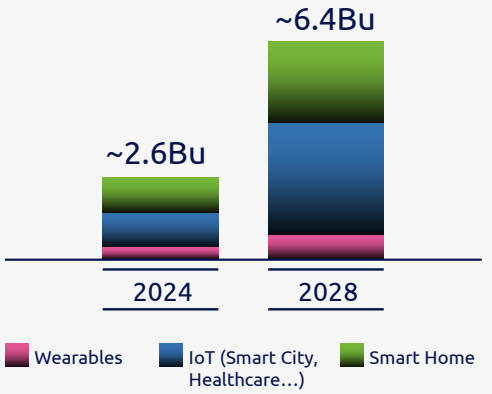
SOI ENGINEERED SUBSTRATES ENABLE BETTER SMART DEVICES

BATTERY POWER SAVINGS

INTEGRATION FROM SOC TO MODULE

SIGNAL INTEGRITY WITH MULTI CONNECTIVITY PROTOCOLS

CONNECTIVITY WIRELESS SMART DEVICES



Source: ABI, 2024

NON-TERRESTRIAL NETWORK (NTN) CONNECTIVITY

5G MOBILE

New NTN bands standardized by 3GPP

Standard mobile phone with RFFE hardware add-on

Soitec Connect products as part of RFFE solution

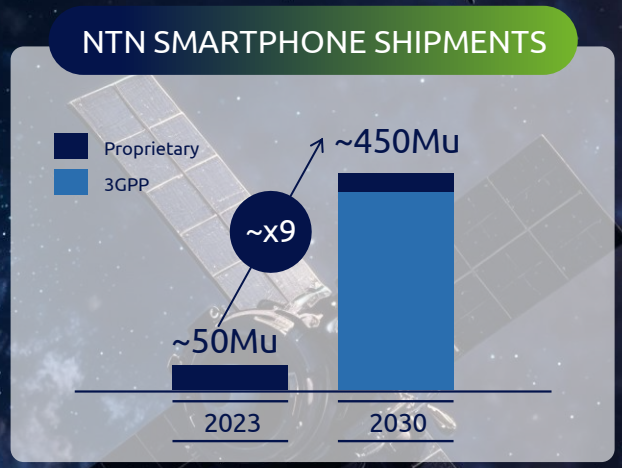
CUSTOMER PREMISES EQUIPMENT NON-TERRESTRIAL NETWORKS

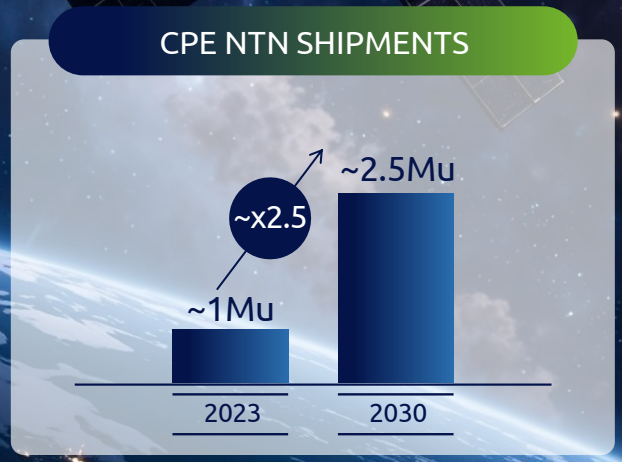
Fully integrated SoC solution reducing footprint

Smaller arrays and lower cost using Connect SOI

Connect SOI solution for low energy power consumption

Source: ADI, 2023





MOBILE COMMUNICATIONS DIVISION GROWTH DRIVERS

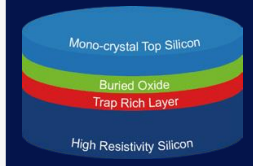
MOBILE COMMUNICATIONS	CURRENT STATUS & SHORT-TERM DYNAMICS	MID & LONG-TERM AMBITIONS
	**SMARTPHONE MARKET TO GROW LOW-SINGLE DIGIT IN 2025 & 2026** **5G TO CONTINUE TO INCREASE MODESTLY (~HIGH 60% CURRENTLY)** **Wi-Fi 6/6E PENETRATION TO EXCEED 60% IN 2025**	**5G & Wi-Fi TO PROGRESS STEADILY – 6G TO ENTER MARKET ~2030** **CONTENT GROWTH DRIVEN BY SMARTPHONE PREMIUMIZATION** **EDGE AI FEATURES TO SUPPORT SMARTPHONE REPLACEMENT CYCLE**
	Reference substrate for smartphone RF FEM (LNAs, Tuners, Switches) Customer inventories to go further down in 2025 New discussions around multi-year contracts Strong leadership, ongoing transition to new products (9SW 300mm)	> 90% Penetration in LNAs, Tuners & Switches Diversification into new 5G advanced & connectivity applications beyond mobile (IoT, Wearables, Satellite Communications, Automotive)
	Only solution for fully integrated 5G mmWave system-on-chip Early adoption for mmWave system-on-chip and envelope trackers Key foundries design wins on FD-SOI platform for mmWave modules	Mainstream technology for mmWave system-on-chip, Ultra Wide Band, Satellite Communications Growing number of mmWave applications
	SAW-on-POI can operate across the entire frequency spectrum 10 customers in volume production, 13 prospects in qualification Engaged with all Key US Fabless New design wins supporting more filter integration in PAMid modules	Adoption by all Tier #1 Fabless for premium and mid-tier smartphones, from low band to mid-high band Addressable market growth through product portfolio expansion

03

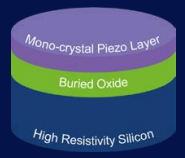
AI x CONNECTIVITY ENHANCED BY ENGINEERED SUBSTRATES

SOITEC PRODUCT PORTFOLIO ENABLES BEST-IN-CLASS CONNECTIVITY

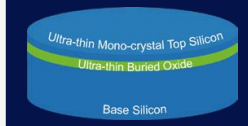
A COMPREHENSIVE OFFER FOR Sub-6GHz & mmWave FRONT-END MODULES



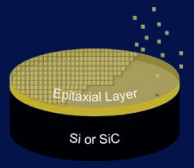
Connect RF-SOI
For highly efficient mobile communications



Connect POI
High performance 5G filters



Connect FD-SOI
Integrated technology



Connect RF-GaN
High-performance power amplifiers

TODAY'S SMARTPHONE: MORE EFFICIENT, LOWER POWER CONSUMPTION, SMALLER FOOTPRINT

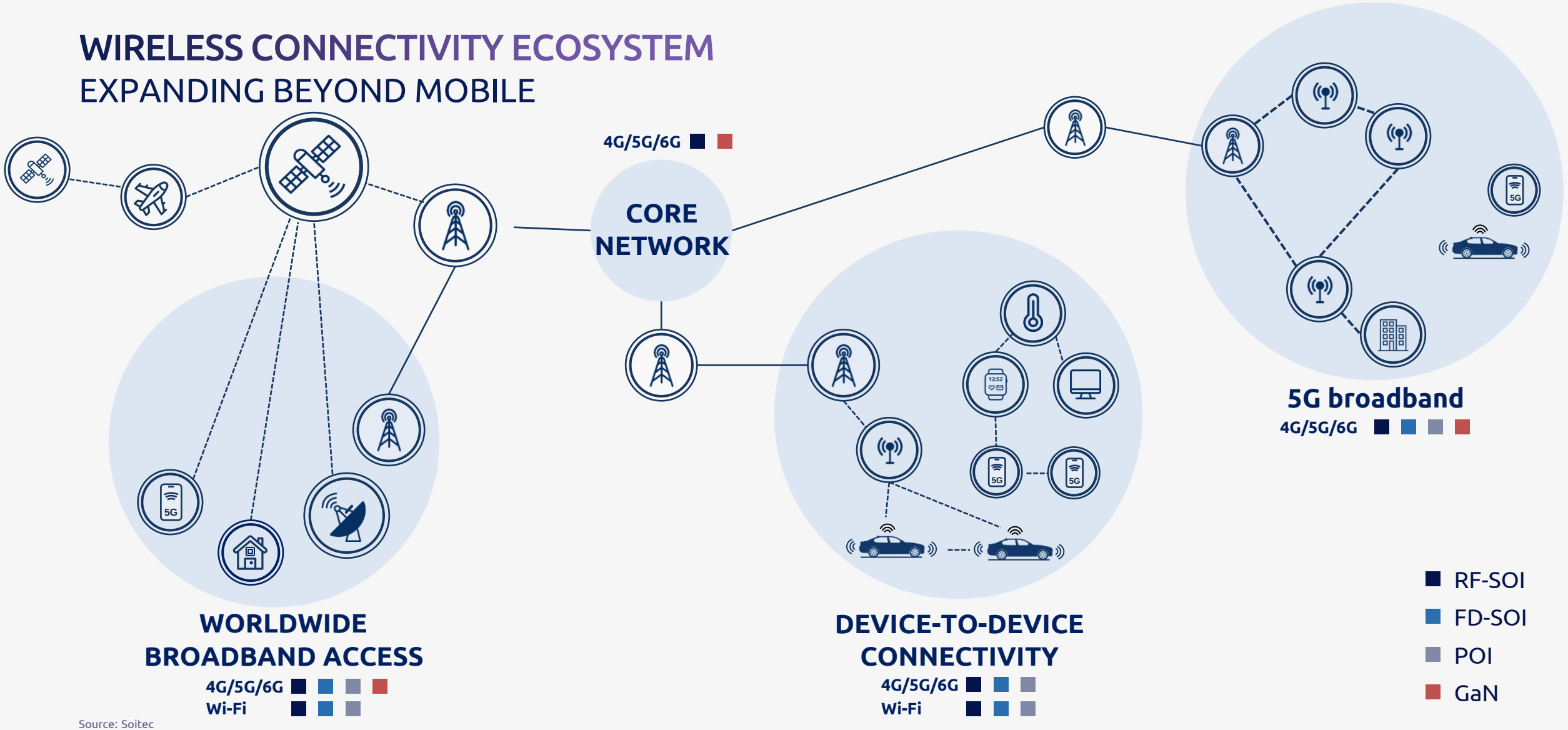
	4G / 5G Sub-6GHz	5G mmWave	Wi-Fi & UWB
POWER AMPLIFIER (PA)		● ●	●
LOW NOISE AMPLIFIER (LNA)	●	● ●	●
SWITCH	●	●	●
ANTENNA TUNER (AT)	●		
FILTER	●		●
ENVELOPE TRACKER (ET)	●		
PHASE SHIFTER		● ●	●
SYSTEM ON CHIP (SoC)		●	●
INTEGRATED FRONT-END		●	●

TOMORROW'S SMARTPHONE – MORE DATA, MORE BANDS: INTEGRATION INTO THE FRONT-END MODULE

	5G	5G Advanced	6G
mmW ANTENNA IN PACKAGE	●	●	●
MIMO UHB	● ●	● ● ●	● ● ●
MIMO MB/HB	● ● ●	● ● ●	● ● ●
MIMO LB	● ● ●	● ● ●	● ● ●
NTN SOS & VOICE	● ●	● ●	● ●
NTN DATA		● ●	● ● ●
MIMO NEW 6GHz BANDS		● ● ●	
MIMO FR3			● ● ● ●

● Connect RF-SOI ● Connect FD-SOI ● Connect POI ● Connect RF-GaN

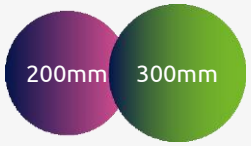
WIRELESS CONNECTIVITY ECOSYSTEM
EXPANDING BEYOND MOBILE

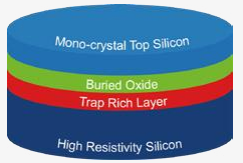


Source: Soitec

CONNECT RF-SOI

Connect RF-SOI embedded in 100% of 5G smartphones





CONNECT RF-SOI EXPANDING LEADERSHIP INTO NEW 5G VERTICALS

5G Communications

Automotive & Industry 4.0

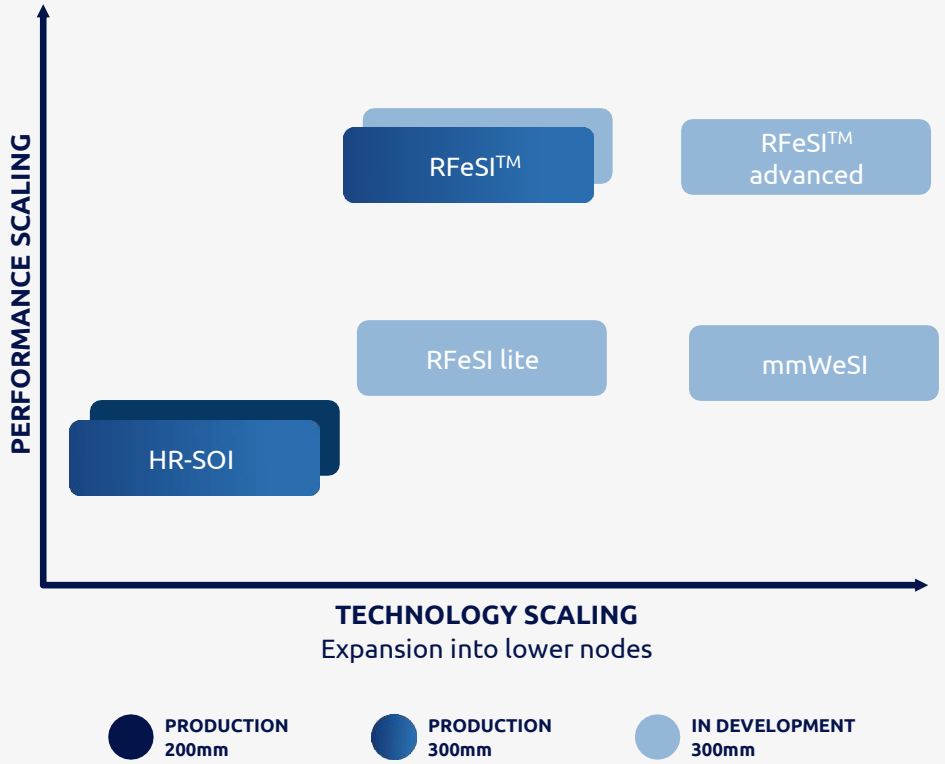
AR / VR

Fixed Wireless Access

OUR RF-SOI SUBSTRATES ENABLE

- 5G Connectivity Enhancement
- Battery Power Saving
- Optimized Footprint with RFFE Integration

CONNECT RF-SOI ROADMAP



CONNECT FD-SOI

FD-SOI for mmWave endorsed by major smartphone OEMs


Samsung Galaxy S25


Google Pixel 9
Google Pixel 9 Pro


Google Pixel 9 Pro Fold


Samsung Galaxy S24


Google Pixel 8
Google Pixel 8 Pro


Google Pixel Fold


Samsung Galaxy Z Flip 6


Samsung Galaxy Z Fold 6


Samsung Galaxy A53

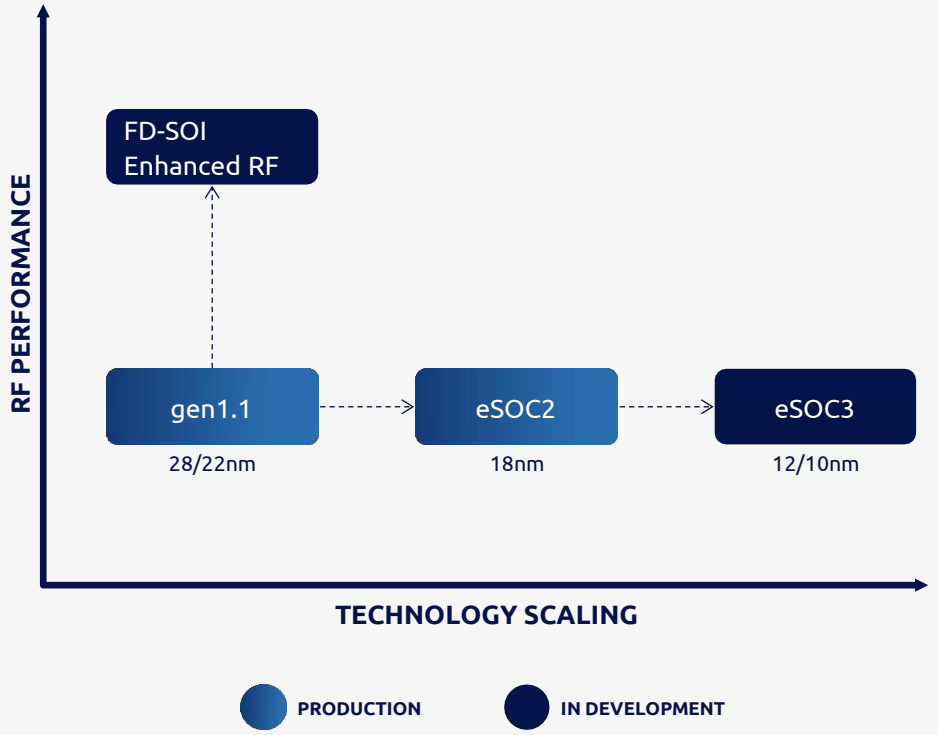

Google Pixel 7
Google Pixel 7 Pro


Google Pixel 6
Google Pixel 6 Pro

OUR FD-SOI SUBSTRATES ENABLE

- High Quality & Extended 5G mmWave Link
- >10% Battery Power Saving
- Optimized Footprint with Digital Scaling

CONNECT FD-SOI ROADMAP



Sources: Samsung, Google

CONNECT FD-SOI
EXPANDING REACH, MAXIMIZING IMPACT

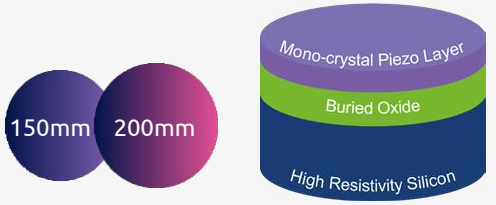
FD-SOI mainstream applications

MEDIATEK Qualcomm SAMSUNG life.augmented

FD-SOI expansion into

CONNECT POI

POI for advanced RF filters penetrating main OEMs



iPhone 16e

Google Pixel 9
Google Pixel 9 Pro

Google Pixel
9 Pro Fold

Samsung
Galaxy Z Flip5

Ray-Ban Meta

OUR POI SUBSTRATES ENABLE

- Better Filter Performance
- Battery Power Saving
- Optimized Filter BOM Footprint

Source: Samsung, Google, Apple, Ray-Ban

CONNECT POI ROADMAP

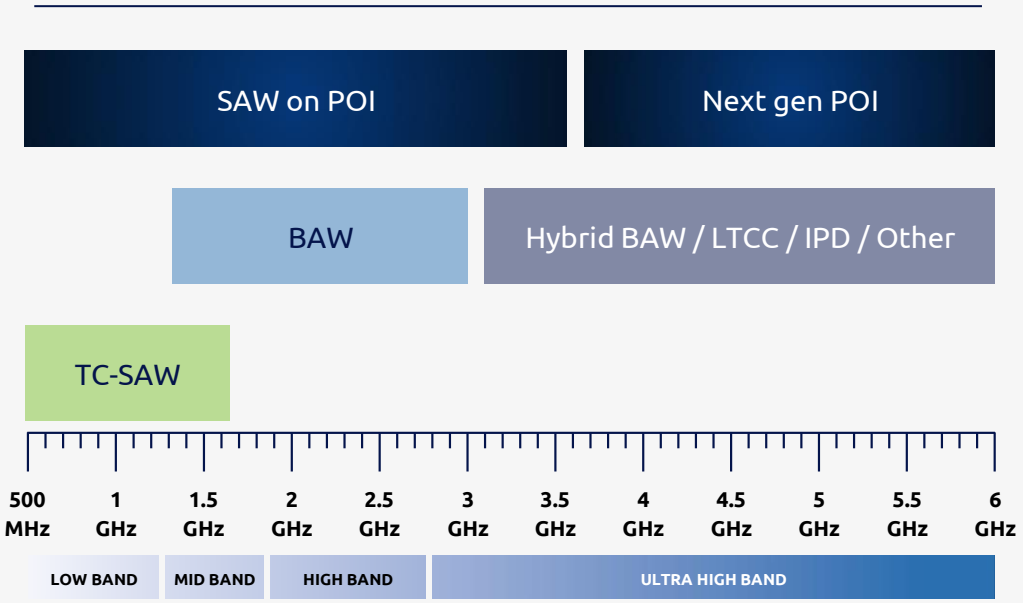
LB: Low Band (0.6-1GHz), **MHB:** Mid-High Band (1.4-2.7GHz), **UHB:** Ultra High Band (>3.3GHz)

LN: Lithium Niobate on Insulator, **LT**: Lithium Tantalate on Insulator

CONNECT POI
WHY CONNECT POI?

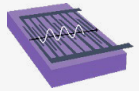
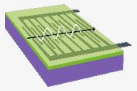
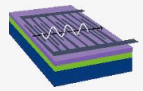
SAW-ON-POI CAN OPERATE ACROSS THE WHOLE FREQUENCY SPECTRUM

Enabling transition to higher bands



SAW-ON-POI ADDRESSES ALL 5G FILTER NEEDS

From higher selectivity to lower insertion losses,
enhanced frequency stability and easier multiplexer integration

	 SAW	 TC-SAW	 BAW	 SAW-on-POI
Substrate	Piezo (non-POI)	Piezo (non-POI)	Piezo (non-POI)	POI
Quality Factor	=	−	+	+
Coupling factor	=	−	=	+
Temperature Compensation	=	+	=	+
Process simplicity	=	−	−	=
Integration	=	=	=	+

CONNECT POI
STRONG VALUE FOUNDATION FOR MARKET EXPANSION

POI customer testimony

"

Tier #1 US: *a* ***"Performance play"***
Tier #1 US: *Soitec POI perform "****better than TC-SAW****"*
Tier #1 US: "***better Qmax than equivalent BAW technology***"
Tier#2 China: *Soitec POI is* ***considered as a "reference"***

"

10 customers in Production

13 customers in Qualification

Engaged with all key players

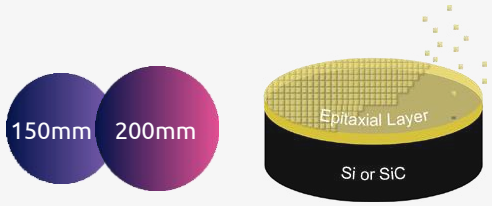
Google Pixel 9 integrates POI from Qorvo & Skyworks

LEADING RF FILTER MANUFACTURERS INTEGRATE SOITEC POI TECHNOLOGY

> *The trend towards using multilayer SAW filters is occurring in flagship smartphones like the Google Pixel 9. Yole Group has identified* ***piezoelectric on insulator (POI) SAW filters in the Google Pixel 9 smartphone supplied by Qorvo and Skyworks****.*

Source: Yole, Google

CONNECT RF-GaN



GaN technology is a standard for RF power amplifiers in 5G MIMO base stations

GaN-on-Silicon is penetrating 5G base station market for 5G radio cost reduction

GaN technology will meet new 5G mobile requirements with new power class devices and new 5G bands

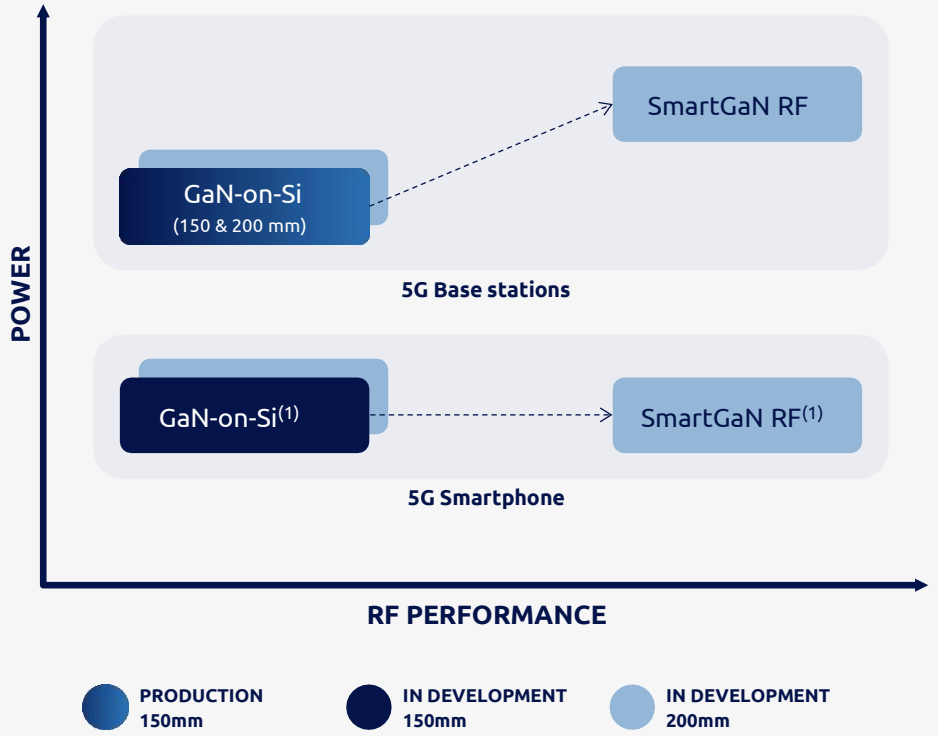
SOITEC CONNECT RF-GaN SOLUTION FOR MOBILE AND INFRASTRUCTURE

Unique expertise to capture **GaN-on-Si** long-term trend for **Mobile & Infrastructure**

Strong experience to serve high volume manufacturing markets

Long-term roadmap to meet higher RF performances with **SmartGaN**

CONNECT RF-GaN ROADMAP



(1)Low voltage compatible

MOBILE COMMUNICATIONS RFFE – ADDRESSING TOMORROW'S CHALLENGES

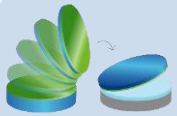
TRENDS TOWARDS 2030

Foldable smartphones increased penetration

Extended module integration

2024

OPTIMIZED FOOTPRINT with



RF-SOI 3D stacking

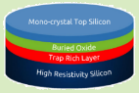
POI Lithium Tantalate for Wide Band

New 6GHz band with higher MIMO

Extended 5G RedCap use cases with 5G Advanced

2026+

MORE STRINGENT FILTER REQUIREMENTS & LOWER COST solution enabled by



RF-SOI next-generation

POI Lithium Niobate for Wide Band

New FR3 band deployment

Wi-Fi 8 emerging

2028+

LOWER POWER & EFFICIENT POWER AMPLIFIER FOR > 10GHz with

SmartGaN

FD-SOI next-generation

> 100GHz 6G data communication

Extended PTP connectivity

2030+

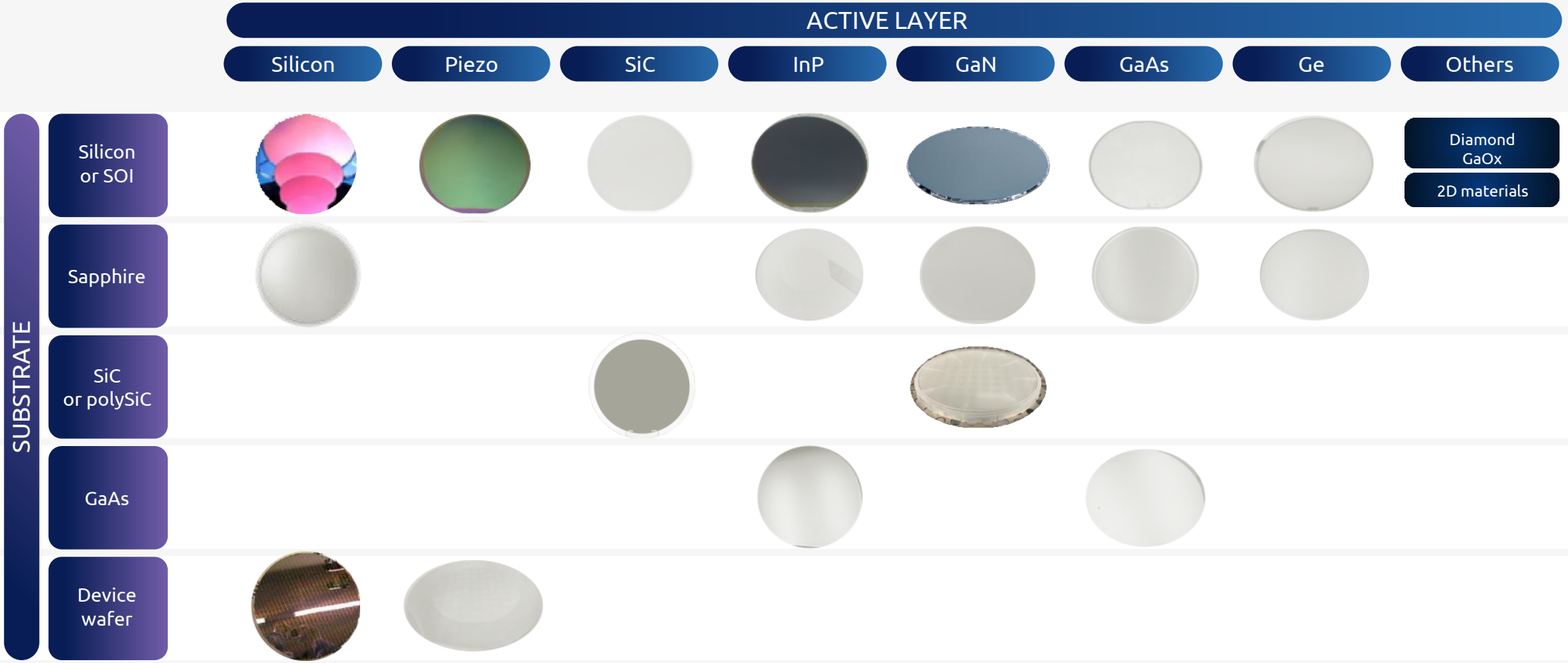
RF TECHNOLOGY SCALING FOR >100GHz with

InP Smart Cut

FD-SOI next-generation

ANYTHING-ON-ANYTHING – SOITEC INNOVATION DNA

EXPANDING PRODUCT PORTFOLIO TO EMPOWER BEST-IN-CLASS CONNECTIVITY



soitec

AI x CONNECTIVITY POWERED BY ENGINEERED SUBSTRATES

THANK YOU

soitec

GLOSSARY

4G LAA	4G License Assisted Access
4G LTE	4G Long-Term Evolution
5G NR-U	5G New Radio Unlicensed
AiP	Antenna-in-Package
BAW	Bulk Acoustic Wave
CPE	Customer Premises Equipment
FTTX	Fiber-to-Anything
FWA	Fixed Wireless Access
IPD	Integrated Passive Devices
LB	Low Band
LNA	Low Noise Amplifier
LTCC	Low Temperature Co-fired Ceramic
MCU	Microcontroller Unit
MHB	Mid-High Band
NTN	Non-Terrestrial Network
RFFE	RF Front-End
SAW	Surface Acoustic Wave
SoC	System-on-Chip
TC-BAW	Temperature Compensated BAW
UHB	Ultra-High band
UWB	Ultra-Wide band
V2x	Vehicle-to-Everything